

March 2013

# FQP27P06 P-Channel QFET® MOSFET

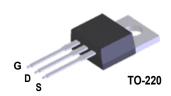
- 60 V, - 27 A, 70 m $\Omega$ 

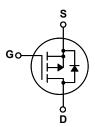
### Description

This P-Channel enhancement mode power MOSFET is produced using Fairchild Semiconductor®'s proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, audio amplifier, DC motor control, and variable switching power applications.

## Features

- - 27 A, 60 V,  $R_{DS(on)}$  = 70 m $\Omega$  (Max.) @  $V_{GS}$  = 10 V,  $I_D$  = 13.5 A
- Low Gate Charge (Typ. 33 nC)
- Low Crss (Typ. 120 pF)
- · 100% Avalanche Tested
- 175°C Maximum Junction Temperature Rating





# Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted

Drain-Source Vo	oltage			Unit
Drain Current	Voltage		-60	V
Drain Current	Current - Continuous (T <sub>C</sub> = 25°C)		-27	Α
	- Continuous (T <sub>C</sub> = 10	0°C)	-19.1	Α
Drain Current	- Pulsed	(Note 1)	-108	Α
Gate-Source Vo	rce Voltage		± 25	V
Single Pulsed Avalanche Energy		(Note 2)	560	mJ
Avalanche Current		(Note 1)	-27	А
Repetitive Avalanche Energy		(Note 1)	12	mJ
Peak Diode Recovery dv/dt		(Note 3)	-7.0	V/ns
Power Dissipation (T <sub>C</sub> = 25°C)			120	W
- Derate above 25°C			0.8	W/°C
Operating and Storage Temperature Range			-55 to +175	°C
Maximum lead temperature for soldering purposes,			300	°C
	Gate-Source Vo Single Pulsed A Avalanche Curro Repetitive Avala Peak Diode Red Power Dissipatio Operating and S Maximum lead t	Gate-Source Voltage Single Pulsed Avalanche Energy Avalanche Current Repetitive Avalanche Energy Peak Diode Recovery dv/dt Power Dissipation (T <sub>C</sub> = 25°C) - Derate above 25°C Operating and Storage Temperature Ra	Gate-Source Voltage Single Pulsed Avalanche Energy (Note 2)  Avalanche Current (Note 1) Repetitive Avalanche Energy (Note 1) Peak Diode Recovery dv/dt (Note 3) Power Dissipation (T <sub>C</sub> = 25°C) - Derate above 25°C Operating and Storage Temperature Range Maximum lead temperature for soldering purposes,	$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$

### **Thermal Characteristics**

Symbol	Parameter	FQP27P06	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case, Max.	1.25	°C/W
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink, Typ.	0.5	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient, Max.	62.5	°C/W

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
Off Cha	aracteristics					
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	-60			V
ΔBV <sub>DSS</sub> / ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	$I_D$ = -250 $\mu$ A, Referenced to 25°C		-0.06		V/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = -60 V, V <sub>GS</sub> = 0 V			-1	μА
		V <sub>DS</sub> = -48 V, T <sub>C</sub> = 150°C			-10	μА
I <sub>GSSF</sub>	Gate-Body Leakage Current, Forward	V <sub>GS</sub> = -25 V, V <sub>DS</sub> = 0 V			-100	nA
I <sub>GSSR</sub>	Gate-Body Leakage Current, Reverse	V <sub>GS</sub> = 25 V, V <sub>DS</sub> = 0 V			100	nA
On Cha	aracteristics					
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250 μA	-2.0		-4.0	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> = -10 V, I <sub>D</sub> = -13.5 A		0.055	0.07	Ω
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = -30 V, I <sub>D</sub> = -13.5 A		12.4		S
Dynam	ic Characteristics					
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = -25 V, V <sub>GS</sub> = 0 V,		1100	1400	pF
C <sub>oss</sub>	Output Capacitance	f = 1.0 MHz		510	660	pF
C <sub>rss</sub>	Reverse Transfer Capacitance			120	155	pF
Switchi	ing Characteristics					
t <sub>d(on)</sub>	Turn-On Delay Time	V - 20 V I - 42 5 A		18	45	ns
t <sub>r</sub>	Turn-On Rise Time	$V_{DD} = -30 \text{ V}, I_{D} = -13.5 \text{ A},$ $R_{G} = 25 \Omega$		185	380	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	NG - 23 12		30	70	ns
t <sub>f</sub>	Turn-Off Fall Time	(Note 4)		90	190	ns
Qg	Total Gate Charge	V <sub>DS</sub> = -48 V, I <sub>D</sub> = -27 A,		33	43	nC
Q <sub>gs</sub>	Gate-Source Charge	V <sub>GS</sub> = -10 V		6.8		nC
Q <sub>gd</sub>	Gate-Drain Charge	(Note 4)		18		nC
	Source Diode Characteristics a	nd Maximum Ratings		l.		I
I <sub>S</sub>	Maximum Continuous Drain-Source Diode Forward Current				-27	Α
I <sub>SM</sub>	Maximum Pulsed Drain-Source Diode Forward Current				-108	Α
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = -27 \text{ A}$			-4.0	V
t <sub>rr</sub>	Reverse Recovery Time	$V_{GS} = 0 \text{ V}, I_{S} = -27 \text{ A},$		105		ns
Q <sub>rr</sub>	Reverse Recovery Charge	dI <sub>F</sub> / dt = 100 A/μs		0.41		μС

**Notes:** 1. Repetitive Rating : Pulse width limited by maximum junction temperature 2. L = 0.9mH, I $_{AS}$  = -27A, V $_{DD}$  = -25V, R $_{G}$  = 25  $\Omega$ , Starting T $_{J}$  = 25°C 3.  $_{SD}$   $\leq$  -27A, di/dt  $\leq$  300A/ $_{HS}$ , V $_{DD}$   $\leq$  BV $_{DSS}$ , Starting T $_{J}$  = 25°C 4. Essentially independent of operating temperature

# **Typical Characteristics**

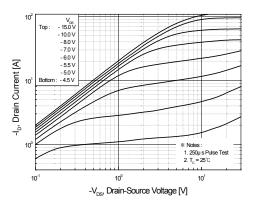


Figure 1. On-Region Characteristics

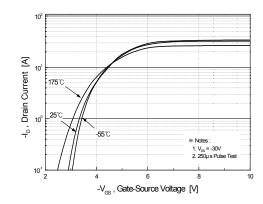


Figure 2. Transfer Characteristics

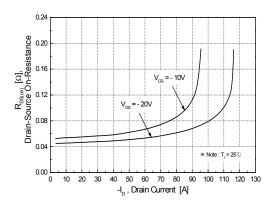


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

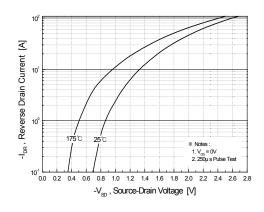


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

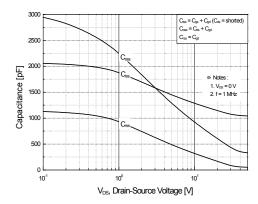


Figure 5. Capacitance Characteristics

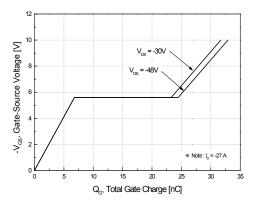


Figure 6. Gate Charge Characteristics

# PV<sub>DSS</sub>. (Normalized.) BV<sub>DSS</sub>. (Normalized.) 10 10 11 \* Notes: 11 \( V\_{08} = 0 \) 2 \( \( \)\_{0} = -20 \) \( \) \

-100

-50

Typical Characteristics (Continued)

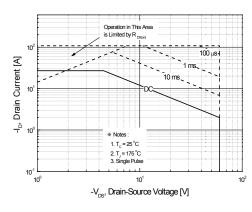
25
(Nomelized)
20
(No

Figure 7. Breakdown Voltage Variation vs. Temperature

T,, Junction Temperature [°C]

150

Figure 8. On-Resistance Variation vs. Temperature



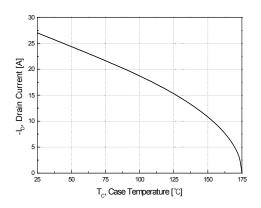


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

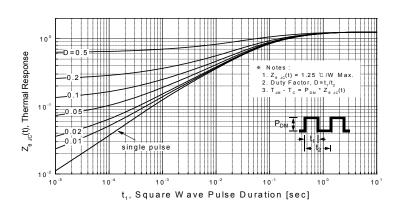
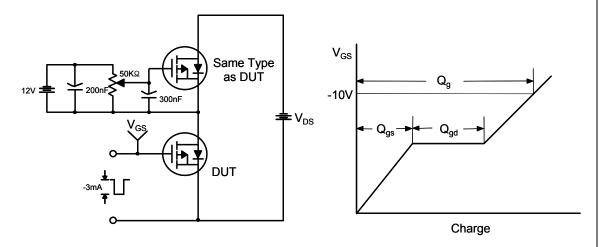
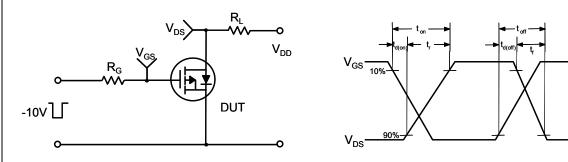


Figure 11. Transient Thermal Response Curve

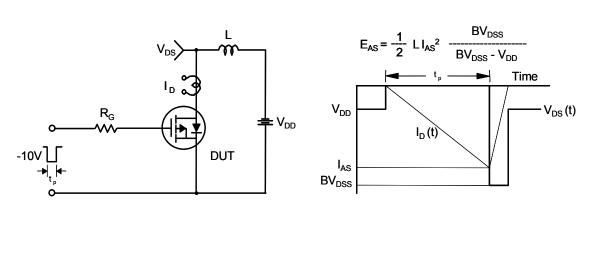
### **Gate Charge Test Circuit & Waveform**



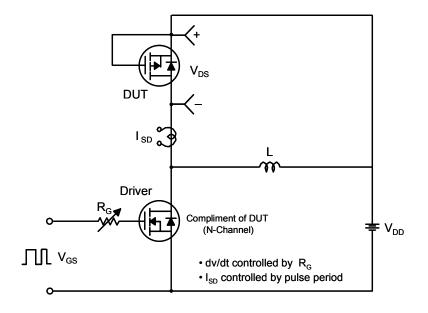
### **Resistive Switching Test Circuit & Waveforms**

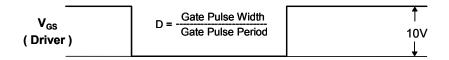


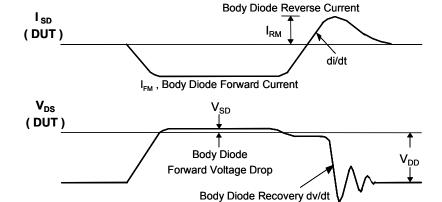
### **Unclamped Inductive Switching Test Circuit & Waveforms**

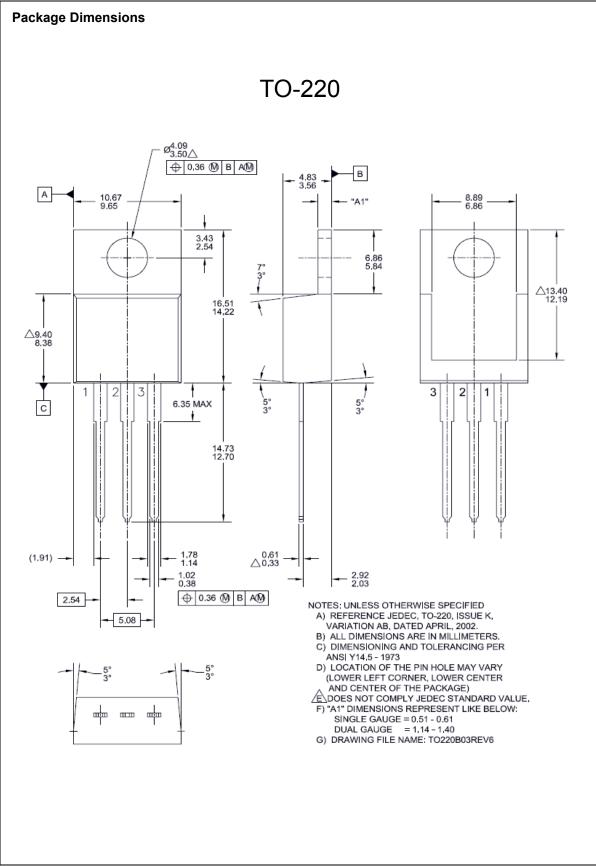


### Peak Diode Recovery dv/dt Test Circuit & Waveforms













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